



## Die Shear Strength

MIL-STD 883 Method 2019

**PURPOSE.** The purpose of this test is to determine the integrity of materials and procedures used to attach semiconductor die or surface mounted passive elements to package headers or other substrates. This determination is based on a measure of force applied to the die, the type of failure resulting from this application of force (if failure occurs) and the visual appearance of the residual die attach media and substrate/header metallization.

### Test Results

Part	Description	Condition	Sample Size	Date	Results
MM1H-0320LCH-2	MMIC Mixer 3 - 20 GHz	-	3	8/29/18	Pass
MM2K-0530LCH-2	MMIC Mixer 5 - 30 GHz	-	2	4/11/18	Pass
MM1K-1140HCH-2	MMIC Mixer RF 11 - 40 GHz	-	2	2/9/18	Pass
MM1H-0320LCH-2	MMIC Mixer 3 - 20 GHz	-	2	1/30/18	Pass
MM1H-1140HCH-2	MMIC Mixer RF 11 - 40 GHz	-	2	1/18/18	Pass

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215 Vineyard Court, Morgan Hill, CA 95037 | Ph: 408.778.4200 | Fax 408.778.4300 | info@markimicrowave.com